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j	Alloert, K., et al., "A Comparison Between Silicon Nitride Films Made by PCVD of N ₂ -SiH ₄ /Ar and N ₂ -SiH ₄ /He," <i>Journal of the Electrochemical Society</i> , Vol. 132, No. 7, pp. 1763-1766, (July 1985).
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EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not conformance and not considered. Include copy of this form with next communication to applicant.